

# **Preliminary Datasheet**

Specifications in this document are tentative and subject to change.

R8C/34P Group, R8C/34R Group RENESAS MCU

R01DS0027EJ0010 Rev.0.10 Jul 05, 2011

#### 1. Overview

#### 1.1 Features

The R8C/34P Group, R8C/34R Group of single-chip MCUs incorporates the R8C CPU core, employing sophisticated instructions for a high level of efficiency. With 1 Mbyte of address space, and it is capable of executing instructions at high speed. In addition, the CPU core boasts a multiplier for high-speed operation processing.

Power consumption is low, and the supported operating modes allow additional power control. These MCUs are designed to maximize EMI/EMS performance.

Integration of many peripheral functions, including multifunction timer and serial interface, reduces the number of system components.

The R8C/34P Group has data flash (1 KB × 4 blocks) with the background operation (BGO) function.

# 1.1.1 Applications

Automobiles and others



# 1.1.2 Specifications

Tables 1.1 and 1.2 outline the Specifications for R8C/34P Group. Tables 1.3 and 1.4 outline the Specifications for R8C/34P Group.

Table 1.1 Specifications for R8C/34P Group (1)

Item	Function	Specification				
CPU	Central processing	R8C CPU core				
	unit	Number of fundamental instructions: 89				
		Minimum instruction execution time:				
		50 ns (f(XIN) = 20 MHz, VCC = 2.7 to 5.5 V)				
		Multiplier: 16 bits × 16 bits → 32 bits				
		<ul> <li>Multiply-accumulate instruction: 16 bits x 16 bits + 32 bits → 32 bits</li> </ul>				
		Operation mode: Single-chip mode (address space: 1 Mbyte)				
Memory	ROM, RAM, Data flash	Refer to Table 1.5 Product List for R8C/34P Group.				
Power Supply	Voltage detection	Power-on reset				
Voltage	circuit	Voltage detection 3 (detection level of voltage detection 1 selectable)				
Detection						
I/O Ports	Programmable I/O	Input-only: 1 pin				
	ports	CMOS I/O ports: 43, selectable pull-up resistor				
Clock	Clock generation	3 circuits: XIN clock oscillation circuit,				
	circuits	High-speed on-chip oscillator (with frequency adjustment function),				
		Low-speed on-chip oscillator				
		Oscillation stop detection: XIN clock oscillation stop detection function				
		• Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16				
		Low power consumption modes:				
		Standard operating mode (high-speed clock, high-speed on-chip oscillator,				
		low-speed on-chip oscillator), wait mode, stop mode				
Interrupts		Number of interrupt vectors: 69				
		• External Interrupt: 9 (INT × 5, Key input × 4)				
		Priority levels: 7 levels				
Watchdog Time	er	• 14 bits x 1 (with prescaler)				
		Reset start selectable				
DTO (D. ). T	( 0 ( 11 )	Low-speed on-chip oscillator for watchdog timer selectable				
DIC (Data Tra	nsfer Controller)	• 1 channel				
		Activation sources: 30     Transfer and deep 2 (sourced and deep and d				
Time ou	Time or DA	Transfer modes: 2 (normal mode, repeat mode)      History 4 (with 8 bit proceeds:)				
Timer	Timer RA	8 bits x 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every				
		period), event counter mode, pulse width measurement mode, pulse period				
		measurement mode				
	Timer RB	8 bits x 1 (with 8-bit prescaler)				
		Timer mode (period timer), programmable waveform generation mode (PWM				
		output), programmable one-shot generation mode, programmable wait one-				
	Timer RC	shot generation mode				
	Timer KC	16 bits x 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode				
		(output 3 pins), PWM2 mode (PWM output pin)				
	Timer RD	16 bits × 2 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode				
		(output 6 pins), reset synchronous PWM mode (output three-phase				
		waveforms (6 pins), sawtooth wave modulation), complementary PWM mode				
		(output three-phase waveforms (6 pins), triangular wave modulation), PWM3				
		mode (PWM output 2 pins with fixed period)				

Table 1.2 Specifications for R8C/34P Group (2)

Item	Function	Specification			
Serial Interface	UART0	1 channel Clock synchronous serial I/O/UART			
	UART2	1 channel			
		Clock synchronous serial I/O/UART, I <sup>2</sup> C mode (I <sup>2</sup> C-bus), IE mode (IEBus), multiprocessor communication function			
Synchronous S	Serial	1 channel			
Communication	n Unit (SSU)				
LIN Module		Hardware LIN: 1 (timer RA, UART0)			
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode			
D/A Converter		8-bit resolution x 2 circuits			
Comparator B		2 circuits			
Flash Memory		<ul> <li>Programming and erasure voltage: VCC = 2.7 to 5.5 V</li> </ul>			
		Programming and erasure endurance: 10,000 times (data flash)			
		1,000 times (program ROM)			
		Program security: ROM code protect, ID code check			
		Debug functions: On-chip debug, on-board flash rewrite function			
		Background operation (BGO) function			
Operating Fred	quency/Supply	f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V)			
Voltage					
Current consur	nption	Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz)			
Operating Amb	ient Temperature	-40 to 85°C (J version)			
		-80 to 125°C (K version) (1)			
Package		48-pin LQFP			
		Package code: PLQP0048KB-A (previous code: 48P6Q-A)			

1. Specify the K version if K version functions are to be used.

Table 1.3 Specifications for R8C/34R Group (1)

Item	Function	Specification
CPU	Central processing	R8C CPU core
	unit	Number of fundamental instructions: 89
		Minimum instruction execution time:
		50 ns (f(XIN) = 20 MHz, VCC = 2.7 to 5.5 V)
		Multiplier: 16 bits × 16 bits → 32 bits
		<ul> <li>Multiply-accumulate instruction: 16 bits x 16 bits + 32 bits → 32 bits</li> </ul>
		Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM	Refer to Table 1.6 Product List for R8C/34R Group.
Power Supply	Voltage detection	Power-on reset
Voltage	circuit	Voltage detection 3 (detection level of voltage detection 1 selectable)
Detection		
I/O Ports	Programmable I/O	Input-only: 1 pin
	ports	CMOS I/O ports: 43, selectable pull-up resistor
Clock	Clock generation	3 circuits: XIN clock oscillation circuit,
	circuits	High-speed on-chip oscillator (with frequency adjustment function),
		Low-speed on-chip oscillator
		Oscillation stop detection: XIN clock oscillation stop detection function
		• Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16
		Low power consumption modes:
		Standard operating mode (high-speed clock, high-speed on-chip oscillator,
		low-speed on-chip oscillator), wait mode, stop mode
Interrupts		Number of interrupt vectors: 69
·		• External Interrupt: 9 (INT × 5, Key input × 4)
		Priority levels: 7 levels
Watchdog Time	er	• 14 bits × 1 (with prescaler)
		Reset start selectable
		Low-speed on-chip oscillator for watchdog timer selectable
DTC (Data Tra	insfer Controller)	• 1 channel
		Activation sources: 30
		Transfer modes: 2 (normal mode, repeat mode)
Timer	Timer RA	8 bits x 1 (with 8-bit prescaler)
		Timer mode (period timer), pulse output mode (output level inverted every
		period), event counter mode, pulse width measurement mode, pulse period
		measurement mode
	Timer RB	8 bits x 1 (with 8-bit prescaler)
		Timer mode (period timer), programmable waveform generation mode (PWM
		output), programmable one-shot generation mode, programmable wait one-
	Timer DC	shot generation mode
	Timer RC	16 bits x 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode
		(output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits × 2 (with 4 capture/compare registers)
		Timer mode (input capture function, output compare function), PWM mode
		(output 6 pins), reset synchronous PWM mode (output three-phase
		waveforms (6 pins), sawtooth wave modulation), complementary PWM mode
		(output three-phase waveforms (6 pins), triangular wave modulation), PWM3
		mode (PWM output 2 pins with fixed period)
	<u> </u>	1 /

Table 1.4 Specifications for R8C/34R Group (2)

Item	Function	Specification
Serial	UART0	1 channel
Interface		Clock synchronous serial I/O/UART
	UART2	1 channel
		Clock synchronous serial I/O/UART, I <sup>2</sup> C mode (I <sup>2</sup> C-bus), IE mode (IEBus), multiprocessor communication function
Synchronous S	Serial	1 channel
Communication	n Unit (SSU)	
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
D/A Converter		8-bit resolution x 2 circuits
Comparator B		2 circuits
Flash Memory		<ul> <li>Programming and erasure voltage: VCC = 2.7 to 5.5 V</li> </ul>
		Programming and erasure endurance: 100 times (program ROM)
		Program security: ROM code protect, ID code check
		Debug functions: On-chip debug, on-board flash rewrite function
Operating Fred Voltage	quency/Supply	f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V)
Current consur	mption	Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz)
Operating Amb	pient Temperature	-40 to 85°C (J version)
		-80 to 125°C (K version) (1)
Package		48-pin LQFP
		Package code: PLQP0048KB-A (previous code: 48P6Q-A)

1. Specify the K version if K version functions are to be used.

#### 1.2 Product List

Table 1.5 lists Product List for R8C/34P Group and Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/34P Group. Table 1.6 lists Product List for R8C/34R Group and Figure 1.2 shows a Part Number, Memory Size, and Package of R8C/34R Group.

Table 1.5 Product List for R8C/34P Group

#### **Current of Jul 2011**

Part No.	ROM C	apacity	RAM	Package Type	Remarks
Fait No.	Program ROM	Data flash	Capacity	Fackage Type	Remarks
R5F21344PJFP (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0048KB-A	J version
R5F21346PJFP (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	
R5F21344PKFP (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0048KB-A	K version
R5F21346PKFP (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	

(D): Under development

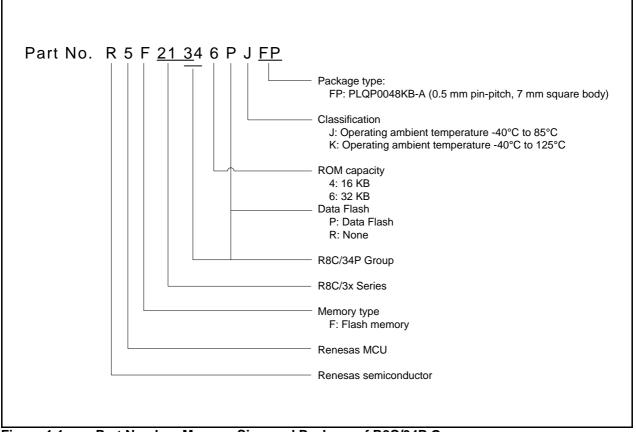


Figure 1.1 Part Number, Memory Size, and Package of R8C/34P Group

Table 1.6 Product List for R8C/34R Group

#### **Current of Jul 2011**

Part No.	ROM Capacity		RAM	Package Type	Remarks
rait No.	Program ROM	Data flash	Capacity	r ackage Type	Remarks
R5F21344RJFP (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0048KB-A	J version
R5F21346RJFP (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	
R5F21344RKFP (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0048KB-A	K version
R5F21346RKFP (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	

(D): Under development

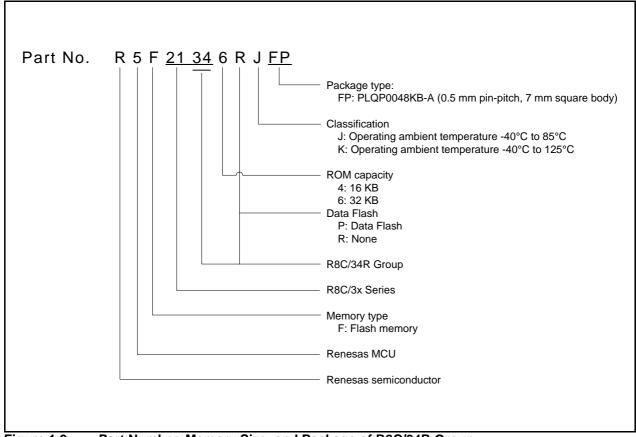


Figure 1.2 Part Number, Memory Size, and Package of R8C/34R Group

# 1.3 Block Diagram

Figure 1.2 shows a Block Diagram.

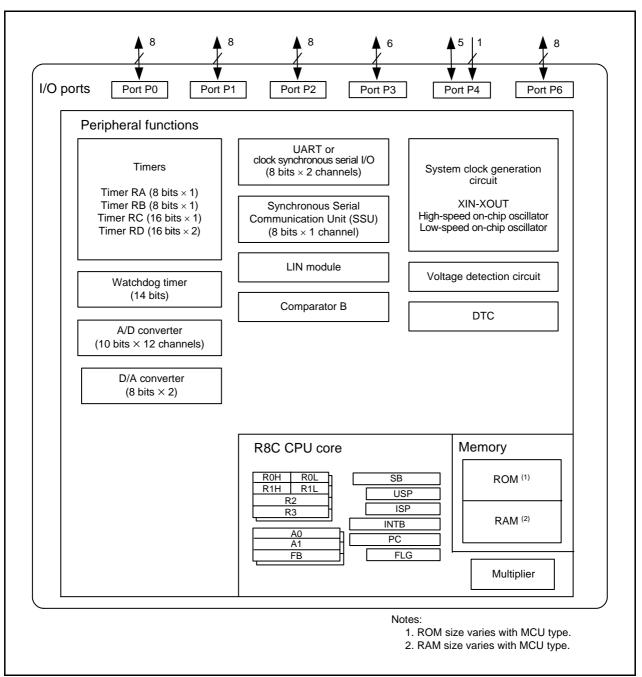


Figure 1.3 Block Diagram

# 1.4 Pin Assignment

R8C/34P Group, R8C/34R Group

Figure 1.4 shows the Pin Assignment (Top View). Table 1.7 outline the Pin Name Information by Pin Number.

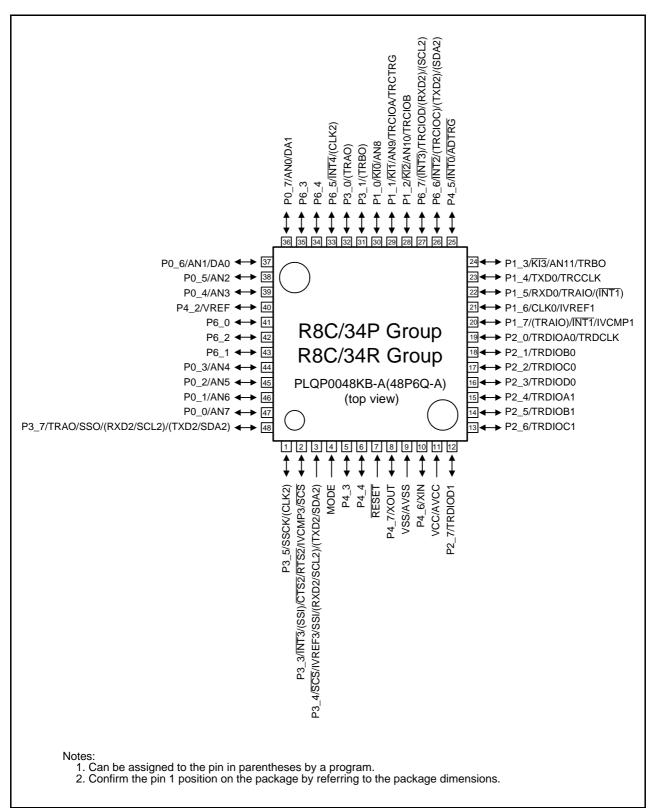


Figure 1.4 Pin Assignment (Top View)

Table 1.7 Pin Name Information by Pin Number

				I/O Pin Funct	ions for Periphera	l Modules	
Pin Number	Control Pin	Port	Interrupt	Timer	Serial Interface	SSU	A/D Converter, D/A Converter, Comparator B
1		P3_5			(CLK2)	SSCK	Comparator B
2		P3_3	ĪNT3		(CTS2/RTS2)	(SSI)/SCS	IVCMP3
3		P3_4			(RXD2/SCL2/	SCS/SSI	IVREF3
					TXD2/SDA2)		_
4	MODE						
5		P4_3					
6		P4_4					
7 8	RESET	D4 7					
9	XOUT VSS/AVSS	P4_7					
10	XIN	P4_6					
11	VCC/AVCC	1					
12		P2_7		TRDIOD1			
13		P2_6		TRDIOC1			
14		P2_5		TRDIOB1			
15 16		P2_4 P2_3		TRDIOA1 TRDIOD0			
17		P2_2		TRDIOC0			
18		P2_1		TRDIOB0			
19		P2_0		TRDIOA0/TRDCLK			
20		P1_7	INT1	(TRAIO)			IVCMP1
21		P1_6			CLK0		IVREF1
22		P1_5	(INT1)	TRAIO	RXD0		
23		P1_4		TRCCLK	TXD0		
24		P1_3	KI3	TRBO			AN11
25		P4_5	ĪNT0				ADTRG
26		P6_6	ĪNT2	(TRCIOC)	(TXD2/SDA2)		
27		P6_7	(INT3)	TRCIOD	(RXD2/SCL2)		
28		P1_2	KI2	TRCIOB	(* " != =, = = =)		
29		P1_1	KI1	TRCIOA/TRCTRG			AN10
30		P1_0	KI0	TROIDATROTRO			AN9
31		P3_1	NIU	(TRBO)			AN8
32		P3_0		(TRAO)			71110
33		P6_5	ĪNT4	( - /	(CLK2)		
34		P6_4			(/		
35		P6_3					
36		P0_7					ANO/DA1
37		P0_6					AN1/DA0
38 39		P0_5 P0_4					AN2 AN3
40		P4_2					VREF
41		P6_0					
42		P6_2					
43		P6_1					
44		P0_3					AN4
45 46		P0_2					AN5 AN6
46		P0_1 P0_0					AN7
48		P3_7		TRAO	(RXD2/SCL2/ TXD2/SDA2)	SSO	7 41 47

1. Can be assigned to the pin in parentheses by a program.

# 1.5 Pin Functions

Tables 1.8 and 1.9 list Pin Functions.

Table 1.8 Pin Functions (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	_	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	-	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	RESET	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between
XIN clock output	XOUT	I/O	the XIN and XOUT pins <sup>(1)</sup> . To use an external clock, input it to the XOUT pin and leave the XIN pin open.
INT interrupt input	INT0 to INT4	I	INT interrupt input pins.
Key input interrupt	KI0 to KI3	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	0	Timer RA output pin
Timer RB	TRBO	0	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Serial interface	CLK0, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD2	I	Serial data input pins
	TXD0, TXD2	0	Serial data output pins
	CTS2	I	Transmission control input pin
	RTS2	0	Reception control output pin
	SCL2	I/O	I <sup>2</sup> C mode clock I/O pin
	SDA2	I/O	I <sup>2</sup> C mode data I/O pin
Synchronous Serial	SSI	I/O	Data I/O pin
Communication	SCS	I/O	Chip-select signal I/O pin
Unit (SSU)	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin

I: Input O: Output

I/O: Input and output

Note:

1. Refer to the oscillator manufacturer for oscillation characteristics.

Table 1.9 Pin Functions (2)

Item	Pin Name	I/O Type	Description
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter and D/A converter
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter
	ADTRG	I	A/D external trigger input pin
D/A converter	DA0, DA1	0	D/A converter output pins
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_7, P6_0 to P6_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually.  Any port set to input can be set to use a pull-up resistor or not by a program.
Input port	P4_2	I	Input-only port

I: Input

O: Output

I/O: Input and output

# 2. Central Processing Unit (CPU)

R8C/34P Group, R8C/34R Group

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.

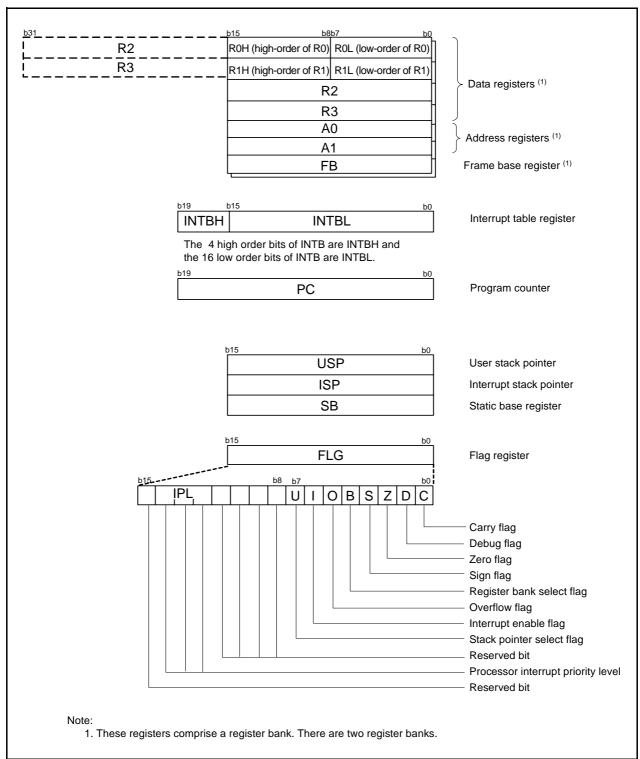


Figure 2.1 CPU Registers

# 2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

#### 2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

# 2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

# 2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

#### 2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

### 2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

### 2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

#### 2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

# 2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

#### 2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

# 2.8.3 **Zero Flag (Z)**

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

### 2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

#### 2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

#### 2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.



# 2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

# 2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

# 2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7. If a requested interrupt has higher priority than IPL, the interrupt is enabled.

#### 2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.



R8C/34P Group, R8C/34R Group

# 3. Memory

# 3.1 R8C/34P Group

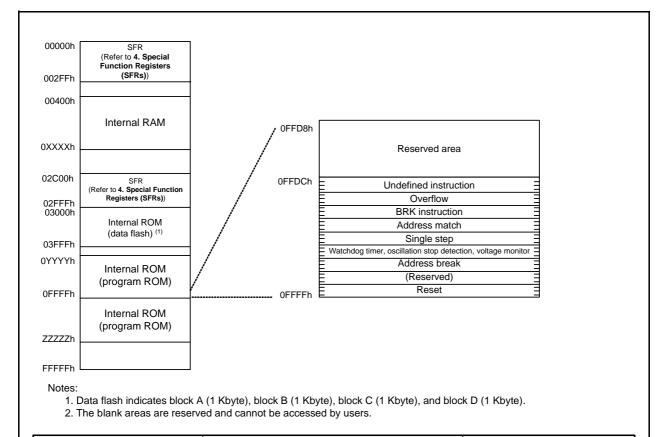
Figure 3.1 is a Memory Map of R8C/34P Group. The R8C/34P Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. For example, a 32-Kbyte internal ROM area is allocated addresses 08000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Part Number		Internal ROM	Internal RAM		
Fait Number	Size	Address 0YYYYh	Address ZZZZZh	Size	Address 0XXXXh
R5F21344PJFP, R5F21344PKFP	16 Kbytes	0C000h	-	1.5 Kbytes	009FFh
R5F21346PJFP, R5F21346PKFP	32 Kbytes	08000h	-	2.5 Kbytes	00DFFh

Figure 3.1 Memory Map of R8C/34P Group

#### 3.2 **R8C/34R Group**

R8C/34P Group, R8C/34R Group

Figure 3.2 is a Memory Map of R8C/34R Group. The R8C/34R Group has a 1-Mbyte address space from addresses 00000h to FFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 32-Kbyte internal ROM area is allocated addresses 08000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.

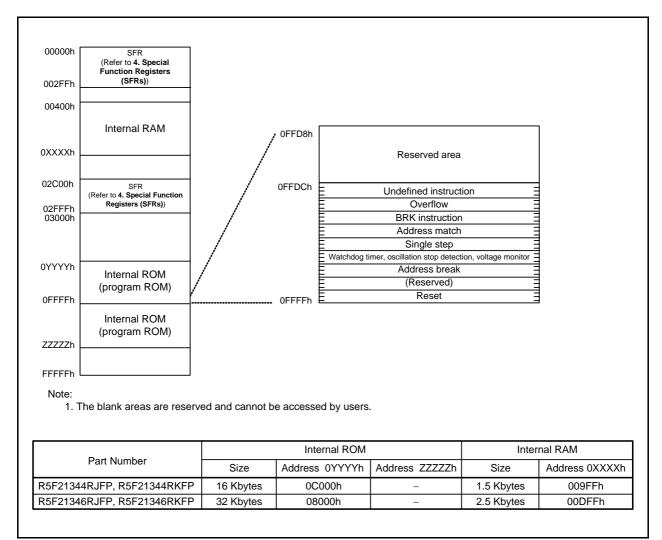


Figure 3.2 Memory Map of R8C/34R Group

#### **Special Function Registers (SFRs)** 4.

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.12 list the special function registers and Table 4.13 lists the ID Code Areas and Option Function Select Area.

Table 4.1 SFR Information (1) (1)

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	00101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Standby Control Register	MSTCR	00h
0009h	System Clock Control Register 3	CM3	00h
000Ah	Protect Register	PRCR	00h
000Bh	Reset Source Determination Register	RSTFR	0XXXXXXXb (2)
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDTC	00111111b
0010h	Training Timor Control Regional	***************************************	001111115
0011h		+	
0011h		-	
0012h			
0013h			
0014h	High-Speed On-Chip Oscillator Control Pogistor 7	FRA7	When shipping
0015h	High-Speed On-Chip Oscillator Control Register 7	FRA/	virien snipping
0016h			
0017h			
0018h			
0019h			
001Bh	Count Counce Destantion Made Desister	CCDD	004
001Ch	Count Source Protection Mode Register	CSPR	00h
			10000000b <sup>(3)</sup>
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h	On-Chip Reference Voltage Control Register	OCVREFCR	00h
0027h			
0028h			
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When Shipping
002Ah	High-Speed On-Chip Oscillator Control Register 5	FRA5	When Shipping
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch			11 3
002Dh			
002Eh			
002Fh	High-Speed On-Chip Oscillator Control Register 3	FRA3	When shipping
0030h	Voltage Monitor Circuit Control Register	CMPA	00h
0031h	Voltage Monitor Circuit Edge Select Register	VCAC	00h
0032h	<u> </u>	1 2	
0033h	Voltage Detect Register 1	VCA1	00001000b
0034h	Voltage Detect Register 2	VCA2	00h (4)
300	10.00g0 20.000 1.00gl0101 2	10,12	00100000b (5)
00356			001000000000
0035h	Voltage Detection 4.Level Colort Devictor	1/041.0	000004445
0036h	Voltage Detection 1 Level Select Register	VD1LS	00000111b
0037h	LV-It Manitan O Circuit Control D	1000	11001/01=: (4)
0038h	Voltage Monitor 0 Circuit Control Register	VW0C	1100X010b <sup>(4)</sup>
			1100X011b <sup>(5)</sup>
0039h	Voltage Monitor 1 Circuit Control Register	VW1C	10001010b

# X: Undefined Notes: 1. The

- The blank areas are reserved and cannot be accessed by users.

  The CWR bit in the RSTFR register is set to 0 after power-on and voltage monitor 0 reset. Hardware reset, software reset, or watchdog timer 2. reset does not affect this bit.
- The CSPROINI bit in the OFS register is set to 0. 3.
- The LVDAS bit in the OFS register is set to 1.
- The LVDAS bit in the OFS register is set to 0.

SFR Information (2) (1) Table 4.2

Address	Register	Symbol	After Reset
003Ah	Voltage Monitor 2 Circuit Control Register	VW2C	10000010b
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			
0040h			
0041h	Flash Memory Ready Interrupt Control Register	FMRDYIC	XXXXX000b
004111 0042h	Trasif Memory Ready Interrupt Control Register	TWINDTIE	XXXXXXXXXX
0042H			
0043H			
0044H			
	INITA laterment Control Desister	INITALO	VVOOVOOR
0046h	INT4 Interrupt Control Register	INT4IC	XX00X000b
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah			
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register	SSUIC	XXXXX000b
0050h	<u> </u>		
0051h	UART0 Transmit Interrupt Control Register	SOTIC	XXXXX000b
0051h	UARTO Receive Interrupt Control Register	SORIC	XXXXX000b
0052h	C. A. C. S. C. SOCIA O I INCITAÇÃO CONTROL PROGRAMO	231410	70000000
0053h			
0054n	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	
	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INTOIC	XX00X000b
005Eh	UART2 Bus Collision Detection Interrupt Control Register	U2BCNIC	XXXXX000b
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0065H			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h	Voltage Monitor 1 Interrupt Control Register	VCMP1IC	XXXXX000b
0072h	Voltage Monitor 2 Interrupt Control Register	VCMP2IC	XXXXX000b
0073h	- Similar I manuar Control Regional	VOINI ZIO	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
0074II			
0075h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
			<u> </u>
007Eh			

X: Undefined
Note:

1. The blank areas are reserved and cannot be accessed by users.

SFR Information (3) (1) Table 4.3

Address	Register	Symbol	After Reset
0080h	DTC Activation Control Register	DTCTL	00h
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h	DTC Activation Enable Register 0	DTCEN0	00h
0089h	DTC Activation Enable Register 1	DTCEN1	00h
008Ah	DTC Activation Enable Register 2	DTCEN2	00h
008Bh	DTC Activation Enable Register 3	DTCEN3	00h
008Ch	DTC Activation Enable Register 4	DTCEN4	00h
008Dh			
008Eh	DTC Activation Enable Register 6	DTCEN6	00h
008Fh	Ĭ		
0090h			
0091h			
0091h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A011	OAKTO Receive Bullet Register	OOKB	XXh
	LIANTO T. IVID. I M. I. D. IVI	110115	
00A8h	UART2 Transmit/Receive Mode Register	U2MR	00h
00A9h	UART2 Bit Rate Register	U2BRG	XXh
00AAh	UART2 Transmit Buffer Register	U2TB	XXh
00ABh			XXh
00ACh	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
00ADh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
00AEh	UART2 Receive Buffer Register	U2RB	XXh
00AFh	1		XXh
00B0h	UART2 Digital Filter Function Select Register	URXDF	00h
00B0H	Oracia Digital Fillor Fullotion Delect Neglotei	OTADI	0011
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			1
00BAh		+	
	LIADTO Chasial Made Desister F	LIOCADE	00h
00BBh	UART2 Special Mode Register 5	U2SMR5	00h
00BCh	UART2 Special Mode Register 4	U2SMR4	00h
00BDh	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
00BEh	UART2 Special Mode Register 2	U2SMR2	X0000000b
00BFh	UART2 Special Mode Register	U2SMR	X0000000b

Note:

1. The blank areas are reserved and cannot be accessed by users.

SFR Information (4) (1) Table 4.4

			A(: D :
Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh	, and the second se		000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D3h	A/D Mode Register	ADMOD	00h
00D4H	A/D Input Select Register	ADINSEL	11000000b
00D3h		ADCONO	00h
	A/D Control Register 0		
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A0 Register	DA0	00h
00D9h	D/A1 Register	DA1	00h
00DAh			
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			<u> </u>
00F3h			
00F4h			
00F5h			<del></del>
00F6h			
00F7h			
00F8h			
00F9h			+
00FAh			+
00FBh			
00FCh			
00506			
00FDh			
00FDh 00FEh 00FFh			

Note:

1. The blank areas are reserved and cannot be accessed by users.

SFR Information (5) (1) Table 4.5

Address	Register	Symbol	After Reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0101h	Timer RA Mode Register	TRAMR	00h
0102h	Timer RA Prescaler Register	TRAPRE	FFh
0103h	Timer RA Register	TRA	FFh
0104h	LIN Control Register 2	LINCR2	00h
0105h	LIN Control Register	LINCR	00h
0100H	LIN Status Register	LINST	00h
0107h	Timer RB Control Register	TRBCR	
		TRBOCR	00h
0109h	Timer RB One-Shot Control Register		00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRE	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h			
0119h			
011Ah			
011Bh			
011Ch			
011Dh			
011Eh			
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0120h	Timer No Counter	TICO	00h
0127H	Timer RC General Register A	TRCGRA	FFh
0128h	Tilliei RC Gelleral Register A	IKCGKA	FFh
0129fi 012Ah	Timer RC General Register B	TDCCDD	FFh
	Timer RC General Register B	TRCGRB	
012Bh	Timer PC Congrel Posicior C	TRCCRC	FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh	LTimes DO Consert Desistes D	TDOODD	FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh	 	TDOODO	FFh
0130h	Timer RC Control Register 2	TRCCR2	00011000b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h	Timer RC Trigger Control Register	TRCADCR	00h
0134h			
0135h			
0136h	Timer RD Trigger Control Register	TRDADCR	00h
0137h	Timer RD Start Register	TRDSTR	11111100b
0138h	Timer RD Mode Register	TRDMR	00001110b
0139h	Timer RD PWM Mode Register	TRDPMR	10001000b
013Ah	Timer RD Function Control Register	TRDFCR	10000000b
013Bh	Timer RD Output Master Enable Register 1	TRDOER1	FFh
013Ch	Timer RD Output Master Enable Register 2	TRDOER2	01111111b
013Dh	Timer RD Output Control Register	TRDOCR	00h
013Eh	Timer RD Digital Filter Function Select Register 0	TRDDF0	00h
013Fh	Timer RD Digital Filter Function Select Register 1	TRDDF1	00h
Note:	Timor NE Eighar Filter Fariotion Coloct Negleter F	ווטטוו	0011

Note:

1. The blank areas are reserved and cannot be accessed by users.

SFR Information (6) (1) Table 4.6

A d draga	Register	Cumbal	After Deact
Address	Timer RD Control Register 0	Symbol	After Reset
0140h	Timer RD I/O Control Register A0	TRDCR0 TRDIORA0	
0141h 0142h	Timer RD I/O Control Register AU  Timer RD I/O Control Register C0	TRDIORAU TRDIORC0	10001000b 10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIORA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h	,		FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh	,		FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh	Timo No Conductive global Di	INDONDI	FFh
0160h		+	
0161h		+	
0161h		+	
0162h			
0164h			
0164h 0165h			
0166h			
0167h			
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah		+	
017Bh		+	
017Ch		+	
017Dh		+	
017Eh		+	-
017Fh		+	-
Villadefined		I	1

Note:

1. The blank areas are reserved and cannot be accessed by users.

SFR Information (7) (1) Table 4.7

Address	Dogistor	Symbol	After Peact
0180h	Register	TRASR	After Reset
	Timer RA Pin Select Register		
0181h	Timer RB/RC Pin Select Register	TRBRCSR	00h
0182h	Timer RC Pin Select Register 0	TRCPSR0	00h
0183h	Timer RC Pin Select Register 1	TRCPSR1	00h
0184h	Timer RD Pin Select Register 0	TRDPSR0	00h
0185h	Timer RD Pin Select Register 1	TRDPSR1	00h
0186h			
0187h			
0188h	UARTO Pin Select Register	U0SR	00h
0189h			
018Ah	UART2 Pin Select Register 0	U2SR0	00h
018Bh	UART2 Pin Select Register 1	U2SR1	00h
018Ch	SSU Pin Select Register	SSUIICSR	00h
018Dh	330 Fili Select Register	33011031	0011
	INT laterwest leavet Dis Colort Desister	INTOD	001-
018Eh	INT Interrupt Input Pin Select Register	INTSR	00h
018Fh	I/O Function Pin Select Register	PINSR	00h
0190h			
0191h			
0192h			
0193h	SS Bit Counter Register	SSBR	11111000b
0194h	SS Transmit Data Register L	SSTDR	FFh
0195h	SS Transmit Data Register H	SSTDRH	FFh
0196h	SS Receive Data Register L	SSRDR	FFh
0197h	SS Receive Data Register H	SSRDRH	FFh
0198h	SS Control Register H	SSCRH	00h
0199h	SS Control Register L	SSCRL	01111101b
	SS Mode Register		00010000b
019Ah		SSMR	
019Bh	SS Enable Register	SSER	00h
019Ch	SS Status Register	SSSR	00h
019Dh	SS Mode Register 2	SSMR2	00h
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A711 01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h	Flash Memory Status Register	FST	10000X00b
01B3h	That memory states register		
01B3h	Flash Memory Control Register 0	FMR0	00h
01B4H	Flash Memory Control Register 1	FMR1	00h
01B5fi 01B6h	Flash Memory Control Register 2	FMR2	00h
	Flash Memory Control Register 2	FMR2	oon
01B7h			
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			
	1	l	İ

Note:

1. The blank areas are reserved and cannot be accessed by users.

SFR Information (8) (1) Table 4.8

Address	Pogiator	Symbol	After Reset
01C0h	Register Address Match Interrupt Register 0	RMAD0	XXh
01C1h	Address Match Interrupt Neglater 0	RWADO	XXh
01C1h	-		0000XXXXb
01C3h	Address Match Interrupt Enable Register 0	AIER0	00h
01C3h	Address Match Interrupt Register 1	RMAD1	XXh
01C4n	Address Match Interrupt Register 1	RWADI	XXh
01C5h	-		
01C6f1	Address Match Interrupt Enable Register 1	AIER1	0000XXXXb 00h
01C/h	Address Match Interrupt Enable Register 1	AIERI	oon
01C8h			
01C9h			
01CAn			
01CCh 01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Pull-Up Control Register 0	PUR0	00h
01E1h	Pull-Up Control Register 1	PUR1	00h
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h			
01F1h			
01F2h			1
01F3h			
01F4h			1
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h		, , , ,	1 00
01F8h	Comparator B Control Register 0	INTCMP	00h
01F9h	Tampanan D domini regions o	11110111	1 00
01FAh	External Input Enable Register 0	INTEN	00h
01FBh	External Input Enable Register 1	INTEN	00h
01FCh	INT Input Filter Select Register 0	INTE	00h
01FDh	INT Input Filter Select Register 0	INTF	00h
01FBh	Key Input Enable Register 0	KIEN	00h
I UIFEII	Les inhat Eliable register o	NIEN	0011
01FFh		II.	

Note:

1. The blank areas are reserved and cannot be accessed by users.

Address	Register	Symbol	After Reset
2C00h	DTC Transfer Vector Area		XXh
2C01h	DTC Transfer Vector Area		XXh
2C02h	DTC Transfer Vector Area		XXh
2C03h	DTC Transfer Vector Area		XXh
2C04h	DTC Transfer Vector Area		XXh
2C05h			XXh
2C06h			XXh
2C07h			XXh
2C08h	DTC Transfer Vector Area		XXh
2C09h	DTC Transfer Vector Area		XXh
2C0Ah	DTC Transfer Vector Area		XXh
2C0Bh	DTC Transfer Vector Area		XXh
2C0Ch			XXh
2C0Dh			XXh
2C0Eh	DTC Transfer Vector Area		XXh
2C0Fh	DTC Transfer Vector Area		XXh
2C10h	DTC Transfer Vector Area		XXh
2C11h	DTC Transfer Vector Area		XXh
2C12h	DTC Transfer Vector Area		XXh
2C13h	DTC Transfer Vector Area		XXh
2C14h			XXh
2C15h			XXh
2C16h	DTC Transfer Vector Area		XXh
2C17h	DTC Transfer Vector Area		XXh
2C18h	DTC Transfer Vector Area		XXh
2C19h	DTC Transfer Vector Area		XXh
2C1Ah	DTC Transfer Vector Area		XXh
2C1Bh	DTC Transfer Vector Area		XXh
2C1Ch	DTC Transfer Vector Area		XXh
2C1Dh	DTC Transfer Vector Area		XXh
2C1Eh	DTC Transfer Vector Area		XXh
2C1Fh	DTC Transfer Vector Area		XXh
2C20h	DTC Transfer Vector Area		XXh
2C21h	DTC Transfer Vector Area		XXh
2C22h			

2C30h			
2C31h	DTC Transfer Vector Area		XXh
2C32h			XXh
2C33h	DTC Transfer Vector Area		XXh
2C34h	DTC Transfer Vector Area		XXh
2C35h			XXh
2C36h			XXh
2C37h			XXh
2C38h			XXh
2C39h			XXh
2C3Ah			XXh
2C3Bh			XXh
2C3Ch			XXh
2C3Dh			XXh
2C3Eh			XXh
2C3Fh			XXh
2C40h	DTC Control Data 0	DTCD0	XXh
2C41h	1		XXh
2C42h	1		XXh
2C43h	7		XXh
2C44h			XXh
2C45h	1		XXh
2C46h	7		XXh
2C47h	7		XXh
2C48h	DTC Control Data 1	DTCD1	XXh
2C49h	7		XXh
2C4Ah	7		XXh
2C4Bh			XXh
2C4Ch			XXh
2C4Dh	7		XXh
2C4Eh	7		XXh
2C4Fh	7		XXh

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.10	SFR Information (10) (1)		
Address	Register	Symbol	After Reset
2C50h	DTC Control Data 2	DTCD2	XXh
2C51h			XXh
2C52h			XXh
2C53h			XXh
2C54h 2C55h			XXh XXh
2C56h			XXh
2C57h			XXh
2C58h	DTC Control Data 3	DTCD3	XXh
2C59h	DTO CONTION DATA 3	D1603	XXh
2C5Ah			XXh
2C5Bh			XXh
2C5Ch			XXh
2C5Dh			XXh
2C5Eh			XXh
2C5Fh			XXh
2C60h	DTC Control Data 4	DTCD4	XXh
2C61h			XXh
2C62h			XXh
2C63h			XXh
2C64h			XXh
2C65h			XXh
2C66h			XXh XXh
2C67h 2C68h	DTC Control Data 5	DTCD5	XXh
2C69h	DTC Control Data 5	ысы	XXh
2C6Ah			XXh
2C6Bh			XXh
2C6Ch			XXh
2C6Dh			XXh
2C6Eh			XXh
2C6Fh			XXh
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2C74h			XXh
2C75h			XXh
2C76h			XXh
2C77h	DT0.0 + 1D + 7	DTOD7	XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h 2C7Ah			XXh XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2C81h			XXh
2C82h			XXh
2C83h			XXh
2C84h			XXh
2C85h			XXh
2C86h			XXh
2C87h	DTO O ID O	DT000	XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah 2C8Bh			XXh XXh
2C8Ch			XXh
2C8Dh	†		XXh
2C8Eh	1		XXh
2C8Fh	1		XXh
2C90h	DTC Control Data 10	DTCD10	XXh
2C91h			XXh
2C92h			XXh
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
X: Undefined		<del></del>	

Note:

1. The blank areas are reserved and cannot be accessed by users.

SFR Information (11) (1) **Table 4.11** 

	The state of the s		
Address	Register	Symbol	After Reset
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah	1		XXh
2C9Bh	1		XXh
2C9Ch	1		XXh
2C9Dh	1		XXh
2C9Eh	-		XXh
	-		
2C9Fh	DT0.0 + 1D + 40	DTODAG	XXh
2CA0h	DTC Control Data 12	DTCD12	XXh
2CA1h			XXh
2CA2h			XXh
2CA3h			XXh
2CA4h	1		XXh
2CA5h	1		XXh
2CA6h	1		XXh
2CA7h	1		XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h	Die Control Data 13	DIGDIS	XXh
2CA3h	4		XXh
2CABh	-		XXh
2CACh			XXh
2CADh			XXh
2CAEh			XXh
2CAFh			XXh
2CB0h	DTC Control Data 14	DTCD14	XXh
2CB1h	1		XXh
2CB2h	1		XXh
2CB3h	†		XXh
2CB4h	-		XXh
2CB5h	-		XXh
2CB6h	1		XXh
2CB7h			XXh
2CB8h	DTC Control Data 15	DTCD15	XXh
2CB9h			XXh
2CBAh			XXh
2CBBh	1		XXh
2CBCh	1		XXh
2CBDh	1		XXh
2CBEh	†		XXh
2CBFh	=		XXh
2CC0h	DTC Control Data 16	DTCD16	XXh
2CC1h	Die Control Data 10	DICDIO	XXh
	4		XXh
2CC2h	4		
2CC3h	_		XXh
2CC4h			XXh
2CC5h			XXh
2CC6h	_		XXh
2CC7h			XXh
2CC8h	DTC Control Data 17	DTCD17	XXh
2CC9h	1		XXh
2CCAh	1		XXh
2CCBh	1		XXh
2CCCh	1		XXh
2CCDh	1		XXh
2CCEh	-		XXh
	4		
2CCFh	DT0.0 + 10 + 40	DTC= :-	XXh
2CD0h	DTC Control Data 18	DTCD18	XXh
2CD1h			XXh
2CD2h	_		XXh
2CD3h			XXh
2CD4h			XXh
2CD5h	1		XXh
2CD6h	1		XXh
2CD7h	1		XXh
2CD8h	DTC Control Data 19	DTCD19	XXh
2CD9h	- Dio Control Data 10	10019	XXh
2CD9h 2CDAh	4		
	4		XXh
2CDBh	4		XXh
2CDCh	_		XXh
2CDDh			XXh
2CDEh			XXh
2CDFh			XXh
X: Undefined			•

Note:

1. The blank areas are reserved and cannot be accessed by users.

**Table 4.12** SFR Information (12) (1)

Address	Register	Symbol	After Reset
2CE0h	DTC Control Data 20	DTCD20	XXh
2CE1h			XXh
2CE2h			XXh
2CE3h			XXh
2CE4h			XXh
2CE5h			XXh
2CE6h			XXh
2CE7h			XXh
2CE8h	DTC Control Data 21	DTCD21	XXh
2CE9h			XXh
2CEAh			XXh
2CEBh			XXh
2CECh			XXh
2CEDh			XXh
2CEEh			XXh
2CEFh			XXh
2CF0h	DTC Control Data 22	DTCD22	XXh
2CF1h			XXh
2CF2h			XXh
2CF3h			XXh
2CF4h			XXh
2CF5h			XXh
2CF6h			XXh
2CF7h			XXh
2CF8h	DTC Control Data 23	DTCD23	XXh
2CF9h			XXh
2CFAh			XXh
2CFBh			XXh
2CFCh			XXh
2CFDh			XXh
2CFEh			XXh
2CFFh			XXh
2D00h			
:			
2FFFh			
X: Undefined			

X: Undefined

#### **Table 4.13 ID Code Areas and Option Function Select Area**

Address	Area Name	Symbol	After Reset
:		<u> </u>	
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:		·	
FFDFh	ID1		(Note 2)
:			•
FFE3h	ID2		(Note 2)
:		_	
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF7h	ID6		(Note 2)
<u>:</u>			
FFFBh	ID7		(Note 2)
:		1050	
FFFFh	Option Function Select Register	OFS	(Note 1)

- The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh.
  - When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user. When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
- The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh. When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user. When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

<sup>1.</sup> The blank areas are reserved and cannot be accessed by users.

#### R8C/34P Group, R8C/34R Group

#### 5. **Electrical Characteristics**

Table 5.1 **Absolute Maximum Ratings** 

Symbol	Parameter	Condition	Rated Value	Unit
Vcc/AVcc	Supply voltage		-0.3 to 6.5	V
Vı	Input voltage (1)		-0.3 to Vcc + 0.3	V
IIN	Input current (1)	(2, 3, 4)	-4 to 4	mA
Vo	Output voltage		-0.3 to Vcc + 0.3	V
Pd	Power dissipation	$-40^{\circ}C \le T_{opr} \le 85^{\circ}C$	300	mW
		$85^{\circ}C < T_{opr} \le 125^{\circ}C$	125	
Topr	Operating ambient temperature		-40 to 85 (J version) / -40 to 125 (K version)	°C
Tstg	Storage temperature		-65 to 150	°C

#### Notes:

- 1. Meet the specified range for the input voltage or the input current.
- Applicable ports: P0 to P2, P3\_0, P3\_1, P3\_3 to P3\_5, P3\_7, P4\_3 to P4\_5, P6
   The total input current must be 12 mA or less.
- 4. Even if no voltage is supplied to Vcc, the input current may cause the MCU to be powered on and operate. When a voltage is supplied to Vcc, the input current may cause the supply voltage to rise. Since operations in any cases other than above are not guaranteed, use the power supply circuit in the system to ensure the supply voltage for the MCU is stable within the specified range.

Table 5.2 Recommended Operating Conditions (1)

Symbol		Dor	ameter		Conditions		Standard		Unit
Symbol		Fale	ametei		Conditions	Min.	Тур.	Max.	Offic
Vcc/AVcc	Supply voltage					2.7	=	5.5	V
Vss/AVss	Supply voltage					-	0	-	V
VIH	Input "H" voltage	Other th	an CMOS ir	nput		0.8 Vcc	-	Vcc	V
		CMOS	Input level	Input level selection	4.0 V ≤ Vcc ≤ 5.5 V	0.5 Vcc	-	Vcc	V
		input	switching	: 0.35 Vcc	2.7 V ≤ Vcc < 4.0 V	0.55 Vcc	-	Vcc	V
			function (I/O port)	Input level selection	4.0 V ≤ Vcc ≤ 5.5 V	0.65 Vcc	-	Vcc	V
			(I/O port)	: 0.5 Vcc	2.7 V ≤ Vcc < 4.0 V	0.7 Vcc	-	Vcc	V
		4.0 V ≤ Vcc ≤ 5.5 V	0.85 Vcc	-	Vcc	V			
				: 0.7 Vcc	2.7 V ≤ Vcc < 4.0 V	0.85 Vcc	=	Vcc	V
		Externa	l clock input	(XOUT)		1.2	=	Vcc	V
VIL	Input "L" voltage	Other th	an CMOS ir	nput		0	-	0.2 Vcc	V
		CMOS	Inputlevel	'	4.0 V ≤ Vcc ≤ 5.5 V	0	=	0.2 Vcc	V
		input switching : 0.35 Vcc	2.7 V ≤ Vcc < 4.0 V	0	-	0.2 Vcc	V		
			function (I/O port)	nort) Input level selection 4.0	4.0 V ≤ Vcc ≤ 5.5 V	0	=	0.4 Vcc	V
			(I/O port)		2.7 V ≤ Vcc < 4.0 V	0	-	0.3 Vcc	V
				Input level selection	4.0 V ≤ Vcc ≤ 5.5 V	0	-	0.55 Vcc	V
				: 0.7 Vcc	2.7 V ≤ Vcc < 4.0 V	0	-	0.45 Vcc	V
		Externa	l clock input	(XOUT)		0	-	0.4	V
IOH(sum)	Peak sum output "H	" current	Sum of all	pins IOH(peak)		-	-	-80	mA
IOH(sum)	Average sum output "	H" current	Sum of all	pins IOH(avg)		-	-	-40	mA
IOH(peak)	Peak output "H" cur	rent				-	-	-10	mA
IOH(avg)	Average output "H"	current				-	-	-5	mA
IOL(sum)	Peak sum output "L'	" current	Sum of all	pins IOL(peak)		-	-	80	mA
IOL(sum)	Average sum output '	L" current	Sum of all	pins IOL(avg)		-	-	40	mA
IOL(peak)	Peak output "L" curr	ent				-	-	10	mA
IOL(avg)	Average output "L"	current				-	-	5	mA
f(XIN)	XIN clock input osci	llation fred	quency		2.7 V ≤ Vcc ≤ 5.5 V	-	-	20	MHz
fOCO40M	When used as the c	ount sour	ce for timer	RC or timer RD (3)	2.7 V ≤ Vcc ≤ 5.5 V	32	-	40	MHz
fOCO-F	fOCO-F frequency				2.7 V ≤ Vcc ≤ 5.5 V	- 1	-	20	MHz
-	System clock freque	ency			2.7 V ≤ Vcc ≤ 5.5 V	_	-	20	MHz
f(BCLK)	CPU clock frequence	у			2.7 V ≤ Vcc ≤ 5.5 V	_	-	20	MHz

- 1. Vcc = 2.7 to 5.5 V and Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
- 2. The average output current indicates the average value of current measured during 100 ms.
- 3. fOCO40M can be used as the count source for timer RC or timer RD in the range of Vcc = 2.7 V to 5.5V.

Table 5.3 Recommended Operating Conditions (2)

Symbol	Parameter		Conditions		Unit		
Symbol	Fai	Parameter		Min.	Тур.	Max.	Offic
IIC(H)	High input injection current	P0 to P2, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6		-	_	2	mA
IIC(L)	Low input injection current P0 to P2, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6			I	_	-2	mA
Σ IIC	Total injection current			=	=	8	mA

1. Vcc = 4.5 to 5.5 V and Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.

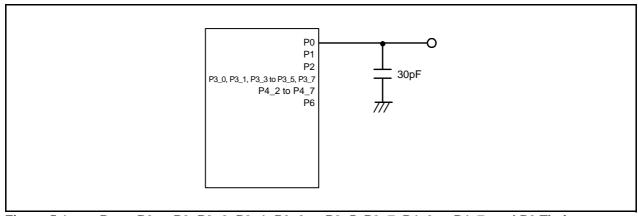


Figure 5.1 Ports P0 to P2, P3\_0, P3\_1, P3\_3 to P3\_5, P3\_7, P4\_2 to P4\_7, and P6 Timing Measurement Circuit

Table 5.4 A/D Converter Characteristics

Symbol	Parameter		Cond	itiono	Standard			Unit
Symbol	Farameter		Conditions		Min.	Тур.	Max.	Offic
=	Resolution		Vref = AVCC		=	-	10	Bit
=	Absolute accuracy	10-bit mode	Vref = AVCC = 5.0 V	AN8 to AN11 input	=	-	±3	LSB
			Vref = AVCC = 3.0 V	AN8 to AN11 input	=	-	±5	LSB
		8-bit mode	Vref = AVCC = 5.0 V	AN8 to AN11 input	=	-	±2	LSB
			Vref = AVCC = 3.0 V	AN8 to AN11 input	=	-	±2	LSB
φAD	A/D conversion clock		4.0 V ≤ Vref = AVCC ≤	5.5 V <sup>(2)</sup>	2	-	20	MHz
			$2.7 \text{ V} \leq \text{Vref} = \text{AVcc} \leq 5.5 \text{ V}$ (2)		2	=	10	MHz
_	Tolerance level impedance				_	3	_	kΩ
tconv	Conversion time	10-bit mode	Vref = AVCC = $5.0 \text{ V}$ , $\phi$	AD = 20 MHz	2.2	-	-	μS
		8-bit mode	Vref = AVCC = $5.0 \text{ V}$ , $\phi$	AD = 20 MHz	2.2	-	-	μS
tsamp	Sampling time		φAD = 20 MHz		0.80	-	-	μS
l∨ref	Vref current (4)		Vcc = 5 V, XIN = f1 =	φAD = 20 MHz	=	45	_	μА
Vref	Reference voltage				2.7	-	AVcc	V
VIA	Analog input voltage (3)				0	-	Vref	V
OCVREF	On-chip reference voltage		$2 \text{ MHz} \le \phi \text{AD} \le 4 \text{ MH}$	Z	1.14	1.34	1.54	V

- 1. Vcc/AVcc = Vref = 2.7 to 5.5 V, Vss = 0 V and Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
- 2. The A/D conversion result will be undefined in wait mode, stop mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
- 3. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.
- 4. When the D/A converter unused.

#### Table 5.5 D/A Converter Characteristics

Symbol	Parameter	Conditions		Unit		
		Conditions	Min.	Тур.	Max.	Offic
_	Resolution		-	=	8	Bit
_	Absolute accuracy		-	-	2.5	LSB
tsu	Setup time		-	-	3	μS
Ro	Output resistor		-	6	-	kΩ
Ivref	Reference power input current	(Note 2)	-	-	1.5	mA

#### Notes:

- 1. VCC/AVCC = Vref = 2.7 to 5.5 V and  $Topr = -40 \text{ to } 85^{\circ}C$  (J version) /  $-40 \text{ to } 125^{\circ}C$  (K version), unless otherwise specified.
- 2. This applies when one D/A converter is used and the value of the DAi register (i = 0 or 1) for the unused D/A converter is 00h. The resistor ladder of the A/D converter is not included.

Table 5.6 Comparator B Electrical Characteristics

Symbol	Parameter	Condition		Unit		
	Farameter	Condition	Min.	Тур.	Max.	Offic
Vref	IVREF1, IVREF3 input reference voltage		0	-	Vcc - 1.4	V
Vı	IVCMP1, IVCMP3 input voltage		-0.3	-	Vcc + 0.3	V
_	Offset		-	5	100	mV
td	Comparator output delay time (2)	Vı = Vref ± 100 mV	-	0.1	-	μS
Ісмр	Comparator operating current	Vcc = 5.0 V	=	17.5	-	μΑ

#### Notes:

- 1. Vcc = 2.7 to 5.5 V,  $T_{opr} = -40$  to  $85^{\circ}C$  (J version) / -40 to  $125^{\circ}C$  (K version), unless otherwise specified.
- 2. When the digital filter is disabled.

Table 5.7 Flash Memory (Program ROM) Electrical Characteristics

Cumbal	Parameter	Conditions		Unit		
Symbol	Parameter	Conditions	Min.	Тур. Мах.		Unit
-	Program/erase endurance (2)	R8C/34P Group	1,000 (3)	-	-	times
		R8C/34R Group	100 (3)	-	-	times
=	Byte program time (program/erase endurance ≤ 100 times)		=	80	300	μS
=	Byte program time (program/erase endurance > 100 times)		=	80	500	μS
_	Block erase time		_	0.3	4	S
td(SR-SUS)	Time delay from suspend request until suspend		=	=	5+CPU clock × 3 cycles	ms
_	Interval from erase start/restart until following suspend request		0	_	_	μS
_	Time from suspend until erase restart		_	_	30+CPU clock × 1 cycle	μS
td(CMDRST- READY)	Time from when command is forcibly terminated until reading is enabled		=	=	30+CPU clock × 1 cycle	μS
=	Program, erase voltage		2.7	=	5.5	V
=	Read voltage		2.7	=	5.5	V
=	Program, erase temperature		-40	=	85 (J version) 125 (K version)	°C
_	Data hold time <sup>(7)</sup>	Ambient temperature = 55°C (8)	20	=	-	year

- 1. Vcc = 2.7 to 5.5 V at Topr = -40 to 85°C (J version) / -40 to 125°C (K version) (under consideration), unless otherwise specified.
- 2. Definition of programming/erasure endurance
  - The programming and erasure endurance is defined on a per-block basis.
  - If the programming and erasure endurance is n (n = 100, 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
  - However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
- 3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
- 4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
- 5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
- 6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
- 7. The data hold time includes time that the power supply is off or the clock is not supplied.
- 8. This data hold time includes 3,000 hours in Ta = 125°C and 7,000 hours in Ta = 85°C.

Table 5.8 Flash Memory (Data flash Block A to Block D) Electrical Characteristics

Cumbal	Parameter	Conditions		Unit		
Symbol		Conditions	Min.	Тур.	Max.	Unit
-	Program/erase endurance (2)		10,000 (3)	=	_	times
=	Byte program time (program/erase endurance ≤ 1,000 times)		=	160	950	μS
=	Byte program time (program/erase endurance > 1,000 times)		=	300	950	μS
=	Block erase time (program/erase endurance ≤ 1,000 times)		=	0.2	1	S
=	Block erase time (program/erase endurance > 1,000 times)		=	0.3	1	S
td(SR-SUS)	Time delay from suspend request until suspend		=	-	3+CPU clock × 3 cycles	ms
=	Interval from erase start/restart until following suspend request		0	ı	-	μS
=	Time from suspend until erase restart		=	_	30+CPU clock x 1 cycle	μS
td(CMDRST- READY)	Time from when command is forcibly terminated until reading is enabled		_	_	30+CPU clock x 1 cycle	μS
_	Program, erase voltage		2.7	-	5.5	V
_	Read voltage		2.7	-	5.5	V
-	Program, erase temperature		-40	-	85°C (J version), 125°C (K version)	°C
_	Data hold time (7)	Ambient temperature = 55 °C (8)	20	1	_	year

- 1. Vcc = 2.7 to 5.5 V and Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
- 2. Definition of programming/erasure endurance

The programming and erasure endurance is defined on a per-block basis.

If the programming and erasure endurance is n (n = 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.

However, the same address must not be programmed more than once per erase operation (overwriting prohibited).

- 3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
- 4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
- 5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
- 6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
- 7. The data hold time includes time that the power supply is off or the clock is not supplied.
- 8. This data hold time includes 3,000 hours in Ta =  $125^{\circ}$ C and 7,000 hours in Ta =  $85^{\circ}$ C.

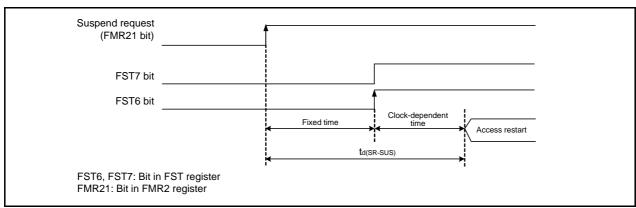


Figure 5.2 Time delay until Suspend

				T		
Symbol	Parameter	Condition	Min.	Standard Typ.	Max.	Unit
Vdet0	Voltage detection level	At the falling of Vcc	2.70	2.85	3.05	V
_	Voltage detection 0 circuit response time (3)	At the falling of Vcc from 5 V to (Vdet0 – 0.1) V	-	6	150	μS
_	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	_	1.5	_	μΑ
td(E-A)	Waiting time until voltage detection circuit operation starts (2)		_	_	100	μS

- 1. The measurement condition is Vcc = 2.7 V to 5.5 V and  $T_{opr} = -40$  to 85°C (J version) / -40 to 125°C (K version).
- 2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
- 3. Time until the voltage monitor 0 reset is generated after the voltage passes Vdeto.

Table 5.10 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition		Unit		
Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
Vdet1	Voltage detection level Vdet1_7 (2)	At the falling of Vcc	2.95	3.25	3.55	V
	Voltage detection level Vdet1_8 (2)	At the falling of Vcc	3.10	3.40	3.70	V
	Voltage detection level Vdet1_9 (2)	At the falling of Vcc	3.25	3.55	3.85	V
	Voltage detection level Vdet1_A (2)	At the falling of Vcc	3.40	3.70	4.00	V
	Voltage detection level Vdet1_B (2)	At the falling of Vcc	3.55	3.85	4.15	V
	Voltage detection level Vdet1_C (2)	At the falling of Vcc	3.70	4.00	4.30	V
	Voltage detection level Vdet1_D (2)	At the falling of Vcc	3.85	4.15	4.45	V
	Voltage detection level Vdet1_E (2)	At the falling of Vcc	4.00	4.30	4.60	V
=	Hysteresis width at the rising of Vcc in voltage detection 1 circuit		=	0.10	-	V
=	Voltage detection 1 circuit response time (3)	At the falling of Vcc from 5 V to (Vdet1_7 – 0.1) V	=	60	150	μS
-	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	_	1.7	_	μΑ
td(E-A)	Waiting time until voltage detection circuit operation starts (4)		=	=	100	μS

#### Notes:

- 1. The measurement condition is Vcc = 2.7 V to 5.5 V and Topr = -40 to 85°C (J version) / -40 to 125°C (K version).
- 2. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
- 3. Time until the voltage monitor 1 interrupt request is generated after the voltage passes Vdet1.
- 4. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 5.11 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition		Unit		
Syllibol	Faranteter	Condition	Min.	Тур.	Max.	Offic
Vdet2	Voltage detection level Vdet2	At the falling of Vcc	3.70	4.00	4.30	V
_	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		-	0.10	-	V
_	Voltage detection 2 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet2 – 0.1) V	-	20	150	μS
_	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	-	1.7	-	μΑ
td(E-A)	Waiting time until voltage detection circuit operation starts <sup>(3)</sup>		-	-	100	μS

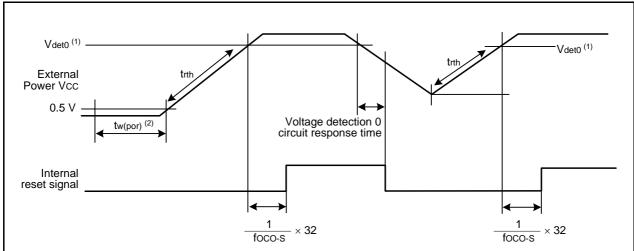
- 1. The measurement condition is Vcc = 2.7 V to 5.5 V and  $T_{opr} = -40$  to  $85^{\circ}C$  (J version) / -40 to  $125^{\circ}C$  (K version).
- 2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes Vdet2.
- 3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.12 Power-on Reset Circuit (2)

Symbol	Parameter	Condition		Unit		
	Falamete	Condition	Min.	Тур.	Max.	Offic
trth	External power Vcc rise gradient	(1)	0	-	50,000	mV/msec

#### Notes:

- 1. The measurement condition is Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
- 2. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.



- Vdeto indicates the voltage detection level of the voltage detection 0 circuit. Refer to 6. Voltage Detection Circuit of User's Manual: Hardware for details.
- 2. tw(por) indicates the duration the external power Vcc must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain tw(por) for 1 ms or more.

Figure 5.3 Power-on Reset Circuit Electrical Characteristics

Table 5.13 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition			Unit	
Symbol	Farameter	Condition	Min.	Тур.	Max.	Offic
_	High-speed on-chip oscillator frequency after reset	Vcc = 2.7 V to 5.5 V, $-40^{\circ}C \le Topr \le 85^{\circ}C (J version) /$	-	40	_	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register <sup>(3)</sup>	-40°C ≤ Topr ≤ 125°C (K version)	-	36.864	-	MHz
	High-speed on-chip oscillator frequency when the FRA6 register correction value is written into the FRA1 register and the FRA7 register correction value into the FRA3 register		-	32	-	MHz
	High-speed on-chip oscillator frequency temperature • supply voltage dependence (2)		<b>-</b> 5	_	5	%
=	Oscillation stability time		=	200	=	μS
-	Self power consumption at oscillation	Vcc = 5.0 V, Topr = 25°C	=	400	=	μА

- 1. The measurement condition is Vcc = 2.7 to 5.5 V,  $T_{opr} = -40$  to 85°C (J version) / -40 to 125°C (K version).
- 2. This indicates the precision error for the oscillation frequency of the high-speed on-chip oscillator.
- 3. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.14 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition		Unit		
Symbol		Condition	Min.	Тур.	Max.	Offic
fOCO-S	Low-speed on-chip oscillator frequency	$2.7 \text{ V} \leq \text{Vcc} < 4.2 \text{ V}$	106.25	125	143.75	kHz
		4.2 V ≤ Vcc ≤ 5.5 V	112.5	125	137.5	
fOCO-WDT	Low-speed on-chip oscillator frequency for watchdog	2.7 V ≤ Vcc < 4.2 V	106.25	125	143.75	kHz
	timer	4.2 V ≤ Vcc ≤ 5.5 V	112.5	125	137.5	
=	Oscillation stability time	Vcc = 5.0 V, Topr = 25°C	=	30	100	μS
_	Self power consumption at oscillation	Vcc = 5.0 V, Topr = 25°C	-	3	-	μА

#### Note:

1. The measurement condition is Vcc = 2.7 to 5.5 V,  $T_{opr} = -40$  to 85°C (J version) / -40 to 125°C (K version).

# **Table 5.15 Power Supply Circuit Timing Characteristics**

Symbol	Parameter	Condition	,	Unit		
	Falametei	Condition	Min.	Тур.	Max.	Unit
td(P-R)	Time for internal power supply stabilization during		=	-	2,000	μS
	power-on (2)					l

- 1. The measurement condition is VCC = 2.7 V to 5.5 V and Topr =  $-40 \text{ to } 85^{\circ}\text{C}$  (J version) /  $-40 \text{ to } 125^{\circ}\text{C}$  (K version).
- 2. Waiting time until the internal power supply generation circuit stabilizes during power-on.

Cumbal	Doromoto	Parameter			Stand	lard	Lloit	
Symbol	Parameter		Conditions	Min.	Тур.	Max.	Unit	
tsucyc	SSCK clock cycle time			4	=	=	tcyc (2)	
tHI	SSCK clock "H" width	SSCK clock "H" width		0.4	1	0.6	tsucyc	
tLO	SSCK clock "L" width			0.4	_	0.6	tsucyc	
trise	SSCK clock rising	Master		-	_	1	tcyc (2)	
	time	Slave		-	1	1	μS	
tFALL	SSCK clock falling time	Master		=	=	1	tcyc (2)	
		Slave		-	1	1	μS	
tsu	SSO, SSI data input	setup time		100	_	=	ns	
tH	SSO, SSI data input I	nold time		1	=	=	tcyc (2)	
tLEAD	SCS setup time	Slave		1tcyc + 50	1	-	ns	
tLAG	SCS hold time	Slave		1tcyc + 50	_	-	ns	
ton	SSO, SSI data output	delay time		-	=	1	tcyc (2)	
tsa	SSI slave access time		2.7 V ≤ Vcc ≤ 5.5 V	-	-	1.5tcyc + 100	ns	
tor	SSI slave out open tir	ne	2.7 V ≤ Vcc ≤ 5.5 V	-	-	1.5tcyc + 100	ns	

- 1. Vcc = 2.7 to 5.5 V, Vss = 0 V and  $T_{opr} = -40$  to  $85^{\circ}C$  (J version) / -40 to  $125^{\circ}C$  (K version), unless otherwise specified.
- 2. 1 tcyc = 1/f1(s)

R8C/34P Group, R8C/34R Group

Figure 5.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

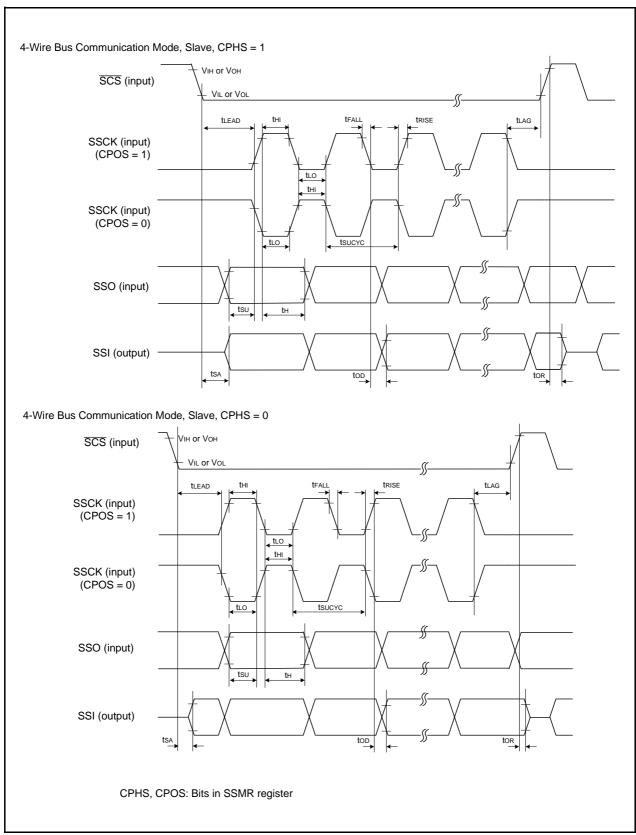


Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

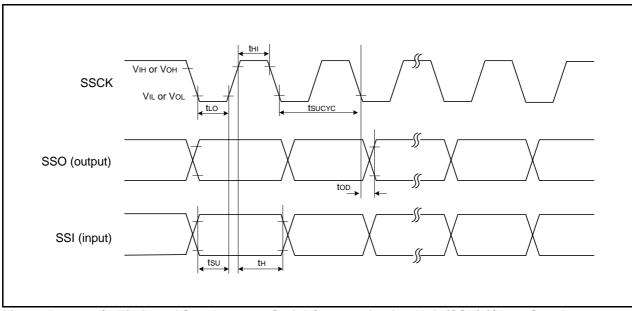


Figure 5.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

Table 5.17 Electrical Characteristics (1) [4.2 V  $\leq$  Vcc  $\leq$  5.5 V]

Symbol	D	Parameter	Condition		Standard		Unit
Symbol	Γ.	arameter	Condition	Min.	Min. Typ.		Offic
Voн	Output "H" voltage	Other than XOUT	Iон = −5 mA	Vcc - 2.0	=	Vcc	V
			IoH = -200 μA	Vcc - 0.3	=	Vcc	V
		XOUT	IOH = -200 μA	1.0	=	Vcc	V
Vol	Output "L" voltage	Other than XOUT	IoL = 5 mA	-	=	2.0	V
			Ιοι = 200 μΑ	-	=	0.45	V
		XOUT	Ιοι = 200 μΑ	-	=	0.5	V
VT+-VT-	Hysteresis	INTO to INT4, KIO to KI3, TRAIO, TRBO, TRCIOA to TRCIOD, TRDIOAO to TRDIODO, TRDIOAI to TRDIODI, TRCCLK, TRCCLK, TRCTRG, ADTRG, RXD0, RXD2, CLK0, CLK2, SSI, SCL2, SDA2, SSO	Vcc = 5.0 V	0.1	1.2	-	V
		RESET	Vcc = 5.0 V	0.1	1.2	_	V
Iн	Input "H" current		VI = 5 V, Vcc = 5.0 V	-	_	1.0	μА
lı∟	Input "L" current		VI = 0 V, Vcc = 5.0 V	-	_	-1.0	μА
RPULLUP	Pull-up resistance		VI = 0 V, Vcc = 5.0 V	25	50	100	kΩ
RfXIN	Feedback resistance	XIN		_	0.3	-	ΜΩ
VRAM	RAM hold voltage		During stop mode	2.0	-	-	V

<sup>1.</sup>  $4.2 \text{ V} \le \text{Vcc} \le 5.5 \text{ V}$  and  $\text{T}_{\text{OPT}} = -40 \text{ to } 85^{\circ}\text{C}$  (J version) /  $-40 \text{ to } 125^{\circ}\text{C}$  (K version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.18 Electrical Characteristics (2) [3.3 V  $\leq$  Vcc  $\leq$  5.5 V] (Topr = -40 to 85°C (J version), unless otherwise specified.)

Symbol	Parameter	er Condition			Standard		
Symbol	i arameter		Condition	Min.	Тур.	Max.	Unit
Icc	Power supply current $(3.3 \text{ V} \leq \text{Vcc} \leq 5.5 \text{ V})$	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	7.0	15	mA
	Single-chip mode, output pins are open, other pins are		XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	=	5.6	12.5	mA
	Vss		XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	3.6	=	mA
		XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	3.0		mA	
		XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	=	2.2	=	mA	
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	1.5	_	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	=	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	3.0	_	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	_	90	180	μА
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	15	110	μА
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	-	5.0	100	μА
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	-	2.0	5.0	μА
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	_	15.0	_	μА

<sup>1.</sup> The typical value (Typ.) indicates the current value when the CPU and the memory operate.

The maximum value (Max.) indicates the current when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Table 5.19 Electrical Characteristics (3) [3.3 V  $\leq$  Vcc  $\leq$  5.5 V] (Topr = -40 to 125°C (K version), unless otherwise specified.)

Symbol	Parameter	Condition			Standard		
Symbol	Farameter		Condition	Min.	Тур.	Max.	Unit
Icc	Power supply current $(3.3 \text{ V} \leq \text{Vcc} \leq 5.5 \text{ V})$	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	7.0	15	mA
	Single-chip mode, output pins are open, other pins are		XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	5.6	12.5	mA
	Vss		XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	3.6	_	mA
		XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	3.0	-	mA	
		XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	2.2	_	mA	
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	1.5	_	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	-	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	3.0	_	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	-	90	400	μΑ
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	-	15	330	μА
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	-	5.0	320	μА
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	-	2.0	5.0	μА
			XIN clock off, Topr = 125°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	_	60	-	μА

The typical value (Typ.) indicates the current value when the CPU and the memory operate.
 The maximum value (Max.) indicates the current when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

# **Timing Requirements**

(Unless Otherwise Specified: Vcc = 5 V, Vss = 0 V at  $Topr = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  (J ver)/ $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  (K ver))

Table 5.20 External Clock Input (XOUT)

Symbol	Parameter		Standard		
			Max.	Unit	
tc(XOUT)	XOUT input cycle time	50	=	ns	
twh(xout)	XOUT input "H" width	24	=	ns	
twl(xout)	XOUT input "L" width	24	=	ns	

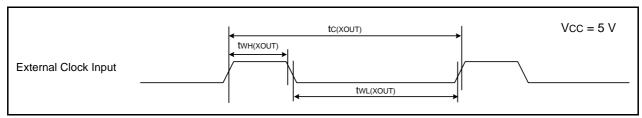


Figure 5.7 External Clock Input Timing Diagram when VCC = 5 V

Table 5.21 TRAIO Input

Symbol	Parameter		Standard		
			Max.	Unit	
tc(TRAIO)	TRAIO input cycle time	100	-	ns	
twh(traio)	TRAIO input "H" width	40	=	ns	
tWL(TRAIO)	TRAIO input "L" width	40	=	ns	

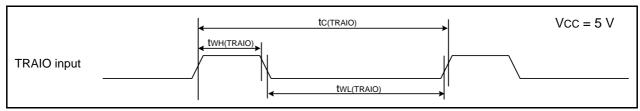


Figure 5.8 TRAIO Input Timing Diagram when Vcc = 5 V

Table 5.22 Serial Interface

Symbol	Parameter	Condition	Stan	Unit	
Symbol	Farameter	Condition	Min.	Max.	Offic
tc(CK)	CLKi input cycle time		200	=	ns
tW(CKH)	CLKi input "H" width		100	=	ns
tW(CKL)	CLKi input "L" width	When external clock selected	100	=	ns
td(C-Q)	TXDi output delay time		=	90	ns
th(C-Q)	TXDi hold time		0	-	ns
tsu(D-C)	RXDi input setup time		10	-	ns
th(C-D)	RXDi input hold time		90	-	ns
td(C-Q)	TXDi output delay time		=	10	ns
tsu(D-C)	RXDi input setup time	When internal clock selected	90	=	ns
th(C-D)	RXDi input hold time		90	=	ns

i = 0, 2

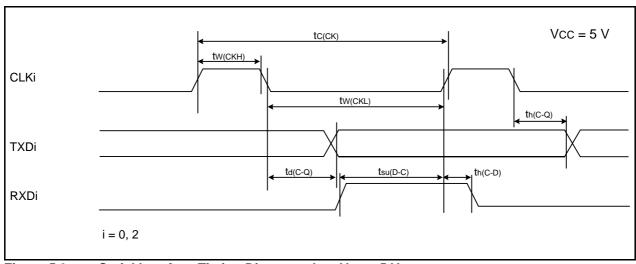


Figure 5.9 Serial Interface Timing Diagram when Vcc = 5 V

Table 5.23 External Interrupt INTi (i = 0 to 4) Input, Key Input Interrupt Kli (i = 0 to 3)

Symbol	Parameter		Standard		
Symbol			Max.	Unit	
tW(INH)	INTi input "H" width, Kli input "H" width		-	ns	
tw(INL)	INTi input "L" width, Kli input "L" width 250 (2)		-	ns	

- 1. When selecting the digital filter by the  $\overline{\text{INTi}}$  input filter select bit, use an  $\overline{\text{INTi}}$  input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
- 2. When selecting the digital filter by the INTi input filter select bit, use an INTi input LOW width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.

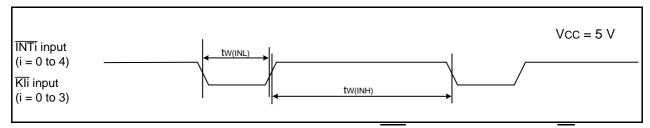


Figure 5.10 Input Timing Diagram for External Interrupt INTi and Key Input Interrupt Kli when Vcc = 5 V

Table 5.24 Electrical Characteristics (4) [2.7 V  $\leq$  Vcc < 4.2 V]

Cumbal	Parameter		Condition		Standard			
Symbol			Condition	Min.	Тур.	Max.	Unit	
Vон	Output "H" voltage	Other than XOUT	Iон = −1 mA	Vcc - 0.5	=	Vcc	V	
		XOUT	IOH = -200 μA	1.0	=	Vcc	V	
Vol	Output "L" voltage	Other than XOUT	IoL = 1 mA	-	=	0.5	V	
		XOUT	Ιοι = 200 μΑ	-	-	0.5	V	
VT+-VT-	Hysteresis  INTO to INT4, KIO to KI3, TRAIO, TRBO, TRCIOA to TRCIOD, TRDIOA0 to TRDIOD0, TRDIOA1 to TRDIOD1, TRCCLK, TRDCLK, TRCTRG, ADTRG, RXD0, RXD2, CLK0, CLK2, SSI, SCL2, SDA2, SSO		Vcc = 3.0 V	0.1	0.4	-	V	
		RESET	Vcc = 3.0 V	0.1	0.5	-	V	
Iн	Input "H" current		VI = 3 V, Vcc = 3.0 V	-	-	1.0	μΑ	
lı∟	Input "L" current		VI = 0 V, Vcc = 3.0 V	=	=	-1.0	μΑ	
RPULLUP	Pull-up resistance		VI = 0 V, Vcc = 3.0 V	42	84	168	kΩ	
RfXIN	Feedback resistance	XIN		_	0.3	=	ΜΩ	
VRAM	RAM hold voltage	<u> </u>	During stop mode	2.0	-	-	V	

<sup>1.</sup>  $2.7 \text{ V} \le \text{Vcc} < 4.2 \text{ V}$  and Topr = -40 to  $85^{\circ}\text{C}$  (J version) / -40 to  $125^{\circ}\text{C}$  (K version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.25 Electrical Characteristics (5) [2.7 V  $\leq$  Vcc < 3.3 V] (Topr = -40 to 85°C (J version), unless otherwise specified.)

Symbol	Parameter		Condition		Standard	b	Unit
	i didiliotoi			Min.	Тур.	Max.	
Icc	(2.7 V < Vcc < 3.3 V) clock mode High-speed on-chip oscillator off	Low-speed on-chip oscillator on = 125 kHz No division	_	7.0	14.5	mA	
	other pins are Vss		XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	5.6	12.0	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	3.6	_	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	3.0	_	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	2.2	-	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	1.5	_	mA
	High-speed on-chip oscillator	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	-	7.0	14.5	mA	
	mode <sup>(1)</sup>	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	=	3.0	=	mA	
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	=	85	180	μА
	Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	15	110	μА	
		XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	=	5	100	μА	
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	=	2.0	5.0	μА
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	-	13.0	-	μА

The typical value (Typ.) indicates the current value when the CPU and the memory operate.
 The maximum value (Max.) indicates the current when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Table 5.26 Electrical Characteristics (6) [2.7 V  $\leq$  Vcc < 3.3 V] (Topr = -40 to 125°C (K version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard Min. Typ. Max.			Unit
					Тур.	Max.	
Icc	Power supply current (2.7 V ≤ Vcc < 3.3 V) Single-chip mode, output pins are open,	High-speed clock mode (1)	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	7.0	14.5	mA
	other pins are Vss		XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	1	5.6	12.0	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	3.6	-	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	3.0	_	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	2.2	-	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	-	1.5	-	mA
		High-speed on-chip oscillator	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	-	7.0	14.5	mA
		mode <sup>(1)</sup>	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	=	3.0	=	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	-	85	390	μА
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	15	320	μА
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	_	5	310	μА
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	-	2.0	5.0	μА
			XIN clock off, Topr = 125°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	-	55.0	-	μА

The typical value (Typ.) indicates the current value when the CPU and the memory operate.
 The maximum value (Max.) indicates the current when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

# **Timing Requirements**

(Unless Otherwise Specified: VCC = 3 V, VSS = 0 V at  $Topr = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  (J ver)/ $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  (K ver))

Table 5.27 External Clock Input (XOUT)

Symbol	Parameter		Standard		
Symbol			Max.	Unit	
tc(XOUT)	XOUT input cycle time	50	=	ns	
twh(xout)	XOUT input "H" width 24 -				
twl(xout)	XOUT input "L" width 24 -				

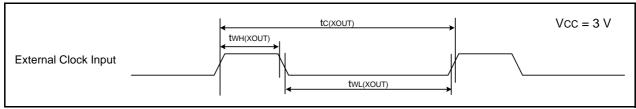


Figure 5.11 External Clock Input Timing Diagram when VCC = 3 V

Table 5.28 TRAIO Input

Symbol	Parameter	Stan	Unit		
Symbol	raidilletei		Max.	Offic	
tc(TRAIO)	TRAIO input cycle time	300	=	ns	
twh(traio)	TRAIO input "H" width 120 –			ns	
tWL(TRAIO)	TRAIO input "L" width 120 –			ns	

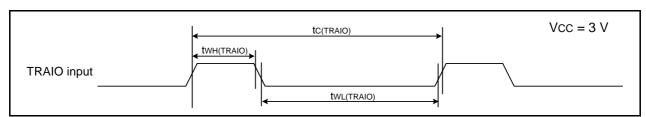


Figure 5.12 TRAIO Input Timing Diagram when Vcc = 3 V

Table 5.29 Serial Interface

Symbol	Parameter	Condition	Stan	Unit	
		Condition	Min.	Max.	Offic
tc(CK)	CLKi input cycle time		300	=	ns
tW(CKH)	CLKi input "H" width		150	=	ns
tW(CKL)	CLKi Input "L" width	When external clock selected	150	=	ns
td(C-Q)	TXDi output delay time		=	120	ns
th(C-Q)	TXDi hold time		0	-	ns
tsu(D-C)	RXDi input setup time			-	ns
th(C-D)	RXDi input hold time		90	-	ns
td(C-Q)	TXDi output delay time		=	30	ns
tsu(D-C)	RXDi input setup time	When internal clock selected	120	=	ns
th(C-D)	RXDi input hold time		90	=	ns

i = 0, 2

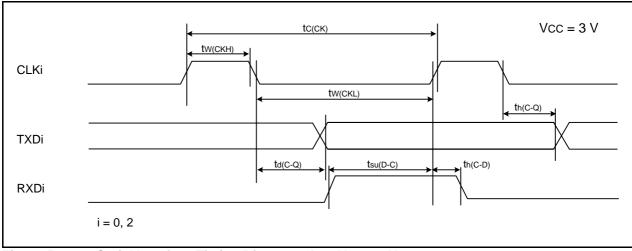


Figure 5.13 Serial Interface Timing Diagram when Vcc = 3 V

Table 5.30 External Interrupt INTi (i = 0 to 4) Input, Key Input Interrupt Kli (i = 0 to 3)

Symbol	Parameter		Standard		
Symbol	Falanielei	Min.	Max.	Unit	
tW(INH)	INTi input "H" width, Kli input "H" width		-	ns	
tW(INL)	INTi input "L" width, Kli input "L" width	-	ns		

- 1. When selecting the digital filter by the  $\overline{\text{INTi}}$  input filter select bit, use an  $\overline{\text{INTi}}$  input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
- 2. When selecting the digital filter by the  $\overline{\text{INTi}}$  input filter select bit, use an  $\overline{\text{INTi}}$  input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

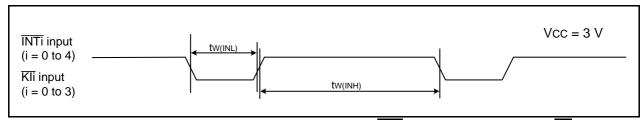
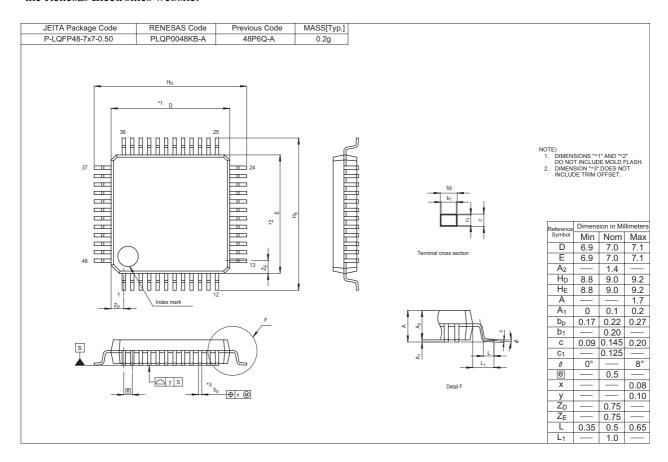


Figure 5.14 Input Timing Diagram for External Interrupt INTi and Key Input Interrupt Kli when Vcc = 3 V

# **Package Dimensions**

R8C/34P Group, R8C/34R Group

Diagrams showing the latest package dimensions and mounting information are available in the "Packages" section of the Renesas Electronics website.



REVISION HISTORY	R8C/34P Group, R8C/34R Group Datasheet
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Rev.	Date		Description
Nev.	Date	Page	Summary
0.01	Sep 30, 2010	_	First Edition issued
0.10	Jul 05, 2011	3	Table 1.2 revised
		5	Table 1.4 revised
		8	Figure 1.3 revised
		11	Table 1.8 revised
		16	3.1 revised
		20	Table 4.3 revised
		26 to 29	Table 4.9 to Table 4.12 revised
		30 to 51	"5. Electrical Characteristics" added

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# General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

#### 1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

## 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

## 3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

 The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

## 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

— When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

# 5. Differences between Products

Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

— The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

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